



Copper

[MIL-C-14550B]

The plated metal is copper in color; and can be deposited matte to very bright. Copper has good corrosion resistance when used as an undercoat. A number of copper processes are available, each designed for a specific purpose;

Bright (to eliminate the need for buffing).

High speed (for electroforming).

Fine grain (to prevent casehardening).

All steel parts having a hardness of Rockwell C35 and higher shall be baked at $375^{\circ}\text{F} \pm 25^{\circ}\text{F}$ for 24 hours within 4 hours after plating to provide hydrogen embrittlement relief. Plated springs and other parts subject to flexure should not be flexed prior to baking operations.

Class 0: (Unless otherwise specified .001-.005") For heat treatment stop-off.

Class 1: (.001" minimum thickness) For carburizing and decarburizing shield, also plated through printed circuit boards.

Class 2: (.0005" minimum thickness) As an undercoat for nickel and other plating.

Class 3: (.0002" minimum thickness) To prevent basis metal migration into tin (prevents poisoning of solderability).

Class 4: (.0001" minimum thickness).